

具有 25 μ A 静态电流的 TPS7A65-Q1 300mA、40V 低压降稳压器

1 特性

- 低压降：
 - 在 $I_{OUT} = 150\text{mA}$ 时为 300mV
- 7V 至 40V 的宽输入电压范围
瞬态电压高达 45V
- 最大输出电流为 300mA
- 轻负载条件下的超低静态电流为 25 μ A（典型值）
- 3.3V 和 5V 固定输出电压，容差为 $\pm 2\%$
- 低 ESR 陶瓷输出稳定电容器
- 集成故障保护：
 - 短路和过流保护
 - 热关断
- 低输入电压跟踪
- 耐热增强型电源封装：
 - 3 引脚 TO-252（KVU、DPAK）

2 应用

- 混合仪表组
- 换挡系统
- 抬头显示
- 汽车仪表组显示屏

3 说明

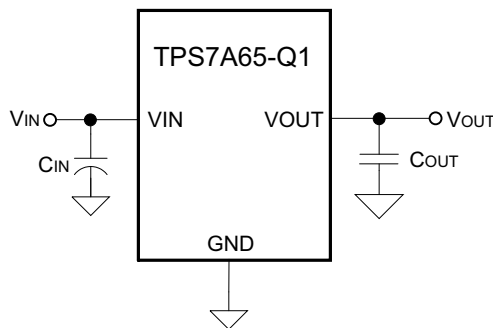
TPS7A65-Q1 低压降线性稳压器专为在轻负载应用中实现低功耗和小于 25 μ A 的静态电流而设计的要求。该器件具有集成式过流保护功能，采用的设计甚至在使用低 ESR 陶瓷输出电容器时也可实现稳定工作。低压跟踪特性允许使用更小的输入电容器并且有可能在冷启动期间无需使用升压转换器。凭借这些特性，此器件非常适合用于各种汽车应用的电源。

器件信息⁽¹⁾

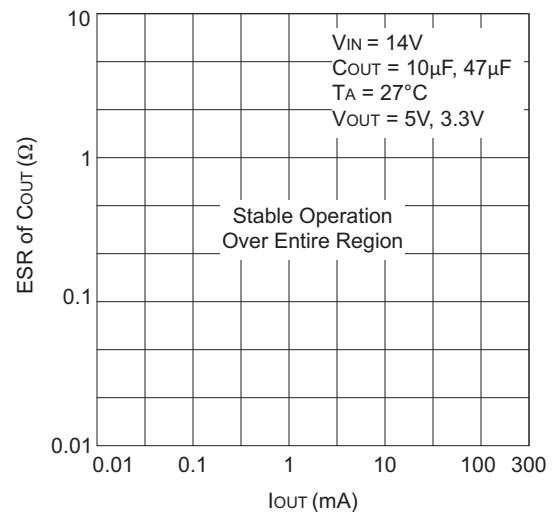
器件型号	封装	封装尺寸（标称值）
TPS7A65-Q1	TO-252 (3)	6.60mm $\times$ 6.10mm

(1) 如需了解所有可用封装，请参阅数据表末尾的封装选项附录。

典型应用电路原理图



典型稳压器稳定性



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4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from Revision E (May 2018) to Revision F	Page
• 已更改 将 11V 更改为 7V（位于 特性 部分的输入电压范围特性 项目符号）	1
• 已更改 更改了应用 部分	1
• Changed V_{IN} parameter minimum specification in <i>Recommended Operating Conditions</i> table from 11 V to 7 V and added footnote	5
• Changed V_{IN} parameter minimum specification in <i>Electrical Characteristics</i> table from 11 V to 7 V and added footnote	6
• Changed 11 V to 7 V in <i>Input voltage range</i> row in <i>Design Parameters</i> table	14
• Changed input voltage range from 11 V to 40 V to 7 V to 40 V in <i>Power Supply Recommendations</i> section	16

Changes from Revision D (December 2015) to Revision E	Page
• 已更改 将 4V 更改为 11V（位于输入电压范围 特性 项目符号）	1
• Changed V_{IN} parameter min specifications to 11 V from 5.3 V and 3.6 V	6
• Changed 4 V to 11 V in <i>Input voltage range</i> row in <i>Design Parameters</i> table	14
• Changed 4 V to 40 V in first sentence of <i>Power Supply Recommendations</i> section	16

Changes from Revision C (December 2011) to Revision D	Page
• 已添加 添加了引脚配置和功能 部分、ESD 额定值 表、特性 说明 部分、器件功能模式 部分、应用和实施 部分、电源相关建议 部分、布局 部分、器件和文档支持 部分以及机械、封装和可订购信息 部分	1

Changes from Revision B (November 2011) to Revision C	Page
• 删除了 TPS7A6533QKVURQ1 器件	1
• Changed the Regulated Output Voltage (5.1). Added to Test Conditions "10mA to 300mA, $V_{IN} = V_{OUT} + 1V$ to 16V"	6

Changes from Revision A (November 2011) to Revision B	Page
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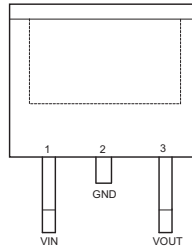
- | | |
|--|---|
| <ul style="list-style-type: none"> • Changed the θ_{JP} value in the Abs Max Table From: 12.7 To: 1.2°C/W | 5 |
|--|---|
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Changes from Original (May 2010) to Revision A	Page
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- | | |
|--|---|
| <ul style="list-style-type: none"> • Removed all KKT information..... | 5 |
|--|---|
-

5 Pin Configuration and Functions

**KVU Package
3-Pin TO-252
Top View**



Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	VIN	I	Input voltage pin: The unregulated input voltage is supplied to this pin. A bypass capacitor is connected between VIN pin and GND pin to dampen input line transients.
2	GND	I/O	Ground pin: This is signal ground pin of the IC.
3	VOUT	O	Regulated output voltage pin: This is a regulated voltage output ($V_{OUT} = 3.3\text{ V}$ or 5 V , as applicable) pin with a limitation on maximum output current. To achieve stable operation and prevent oscillation, an external output capacitor (C_{OUT}) with low ESR is connected between this pin and the GND pin.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{IN}	Unregulated input ⁽²⁾⁽³⁾		45	V
V _{OUT}	Regulated output		7	V
θ _{JP}	Thermal impedance junction to exposed pad		1.2	°C/W
T _A	Operating ambient temperature		125	°C
T _{stg}	Storage temperature	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Absolute negative voltage on these pins not to go below –0.3 V.
- (3) Absolute maximum voltage for duration less than 480 ms.

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge Human body model (HBM), per AEC Q100-002 ⁽¹⁾	±2000	V

- (1) AEC Q100-002 indicates HBM stressing is done in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 Recommended Operating Conditions

		MIN	MAX	UNIT
V _{IN}	Unregulated input voltage	7 ⁽¹⁾	40	V
V _{EN}	Enable pin voltage	4	40	V
T _J	Operating junction temperature	–40	150	°C

- (1) V_{IN} can go down to 4 V for 130 ms or less and remain functional. If V_{IN} is less than 7 V for longer than 130 ms, then some devices may turn off until the input voltage rises above 7 V.

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾			TPS7A65-Q1	UNIT
			KVU (TO-252)	
			3 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	High-K profile ⁽²⁾	29.3	°C/W
		Low-K profile ⁽³⁾	38.6	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance		N/A	°C/W
R _{θJB}	Junction-to-board thermal resistance		8.2	°C/W
ψ _{JT}	Junction-to-top characterization parameter		3.4	°C/W
ψ _{JB}	Junction-to-board characterization parameter		8.1	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance		1.1	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.
- (2) The thermal data is based on JEDEC standard high-K profile – JESD 51-5. The copper pad is soldered to the thermal land pattern. Also correct attachment procedure must be incorporated.
- (3) The thermal data is based on JEDEC standard low-K profile – JESD 51-3. The copper pad is soldered to the thermal land pattern. Also correct attachment procedure must be incorporated.

6.5 Electrical Characteristics

 $V_{IN} = 14\text{ V}$, $T_J = -40^{\circ}\text{C}$ to $+150^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
INPUT VOLTAGE (VIN Pin)						
VIN	Input voltage	Fixed 5-V output, IOUT = 1 mA	7 ⁽¹⁾		40	V
		Fixed 3.3-V output, IOUT = 1 mA	7 ⁽¹⁾		40	
IQUIESCENT	Quiescent current	VIN = 8.2 V to 18 V, IOUT = 0.01 mA to 0.75 mA		25	40	μA
VIN-UVLO	Undervoltage lockout voltage	Ramp VIN down until output is turned OFF		3.16		V
VIN(POWERUP)	Power-up voltage	Ramp VIN up until output is turned ON		3.45		V
REGULATED OUTPUT VOLTAGE (VOUT Pin)						
VOUT	Regulated output voltage	Fixed VOUT value (3.3 V or 5 V as applicable), IOUT = 10 mA, 10 mA to 300 mA, VIN = VOUT + 1 V to 16 V	−2%		2%	
ΔVLINE-REG	Line regulation	VIN = 6 V to 28 V, IOUT = 10 mA, VOUT = 5 V			15	mV
		VIN = 6 V to 28 V, IOUT = 10 mA, VOUT = 3.3 V			20	
ΔVLOAD-REG	Load regulation	IOUT = 10 mA to 300 mA, VIN= 14 V, VOUT = 5 V			25	mV
		IOUT = 10 mA to 300 mA, VIN = 14 V, VOUT = 3.3 V			35	
VDROPOUT ⁽²⁾	Dropout voltage (VIN − VOUT)	IOUT = 250 mA			500	mV
		IOUT = 150 mA			300	
RSW ⁽³⁾	Switch resistance	VIN to VOUT resistance			2	Ω
IOUT	Output current	VOUT in regulation	0		300	mA
ICL	Output current limit	VOUT = 0 V (VOUT pin is shorted to ground)	350		1000	mA
PSRR ⁽³⁾	Power-supply ripple rejection	VIN-RIPPLE = 0.5 Vpp, IOUT = 300 mA, frequency = 100 Hz, VOUT = 5 V, VOUT = 3.3 V		60		dB
		VIN-RIPPLE = 0.5 Vpp, IOUT = 300 mA, frequency = 150 kHz, VOUT = 5 V, VOUT = 3.3 V		30		
TEMPERATURE						
TSHUTDOWN	Thermal shutdown trip point			165		°C
THYST	Thermal shutdown hysteresis			10		°C

- (1) V_{IN} can go down to 4 V for 130 ms or less and remain functional. If V_{IN} is less than 7 V for longer than 130 ms, then some devices may turn off until the input voltage rises above 7 V.
- (2) This test is done with V_{OUT} in regulation and $V_{IN} - V_{OUT}$ parameter is measured when V_{OUT} (3.3 V or 5 V) drops by 100 mV at specified loads.
- (3) Specified by design; not tested.

6.6 Dissipation Ratings

JEDEC STANDARD	PACKAGE	$T_A < 25^{\circ}\text{C}$ POWER RATING (W)	DERATING FACTOR ABOVE $T_A = 25^{\circ}\text{C}$ ($^{\circ}\text{C}/\text{W}$)	$T_A = 85^{\circ}\text{C}$ POWER RATING (W)
JEDEC Standard PCB - low K, JESD 51-3	3-pin KVVU	3.24	38.6	1.68
JEDEC Standard PCB - high K, JESD 51-5	3-pin KVVU	4.27	29.3	2.22

6.7 Typical Characteristics

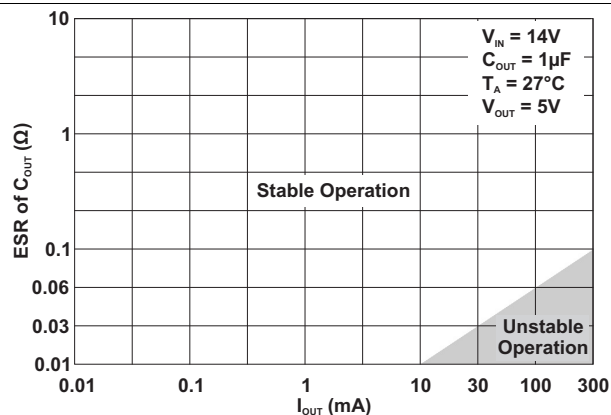


Figure 1. ESR vs Load Current

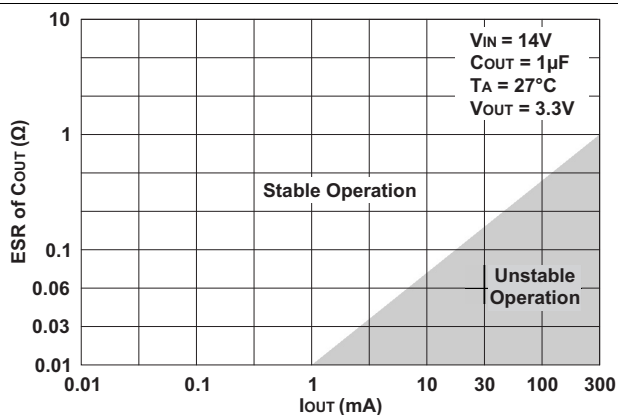


Figure 2. ESR vs Load Current

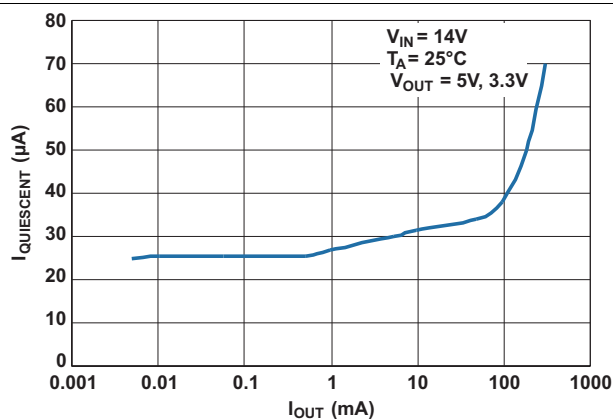


Figure 3. Quiescent Current vs Load Current

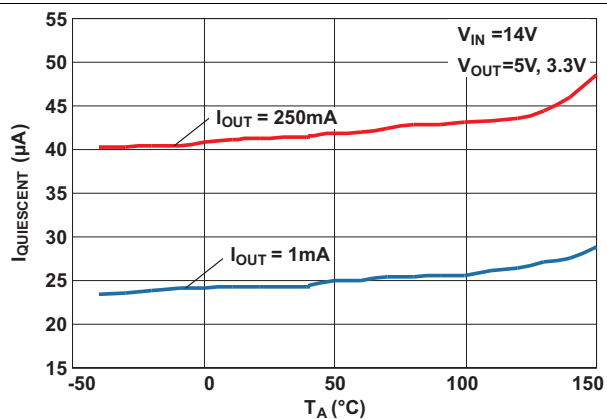


Figure 4. Quiescent Current vs Ambient Air Temperature

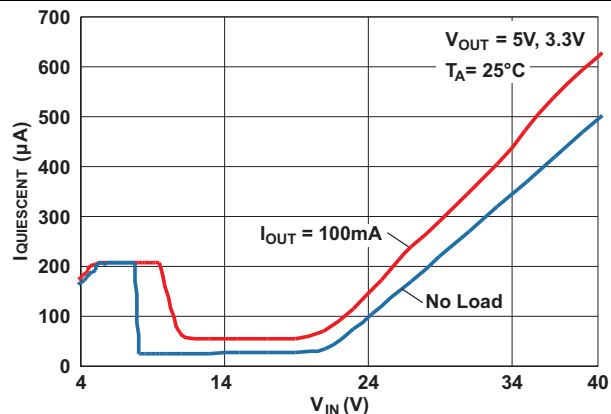


Figure 5. Quiescent Current vs Input Voltage

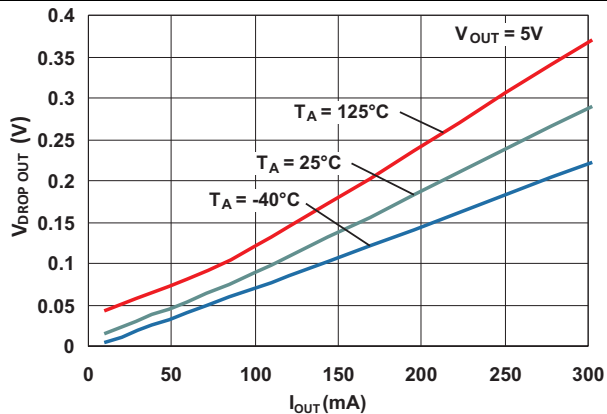
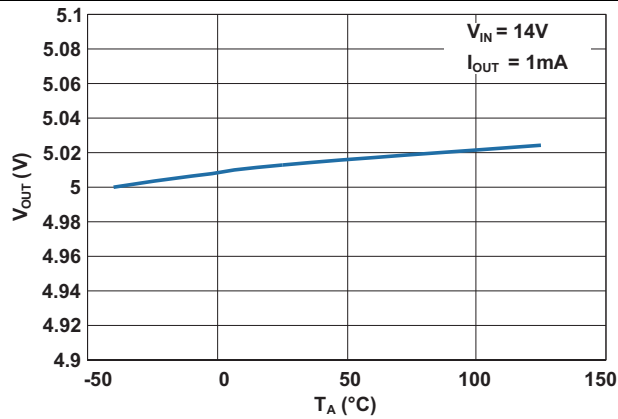
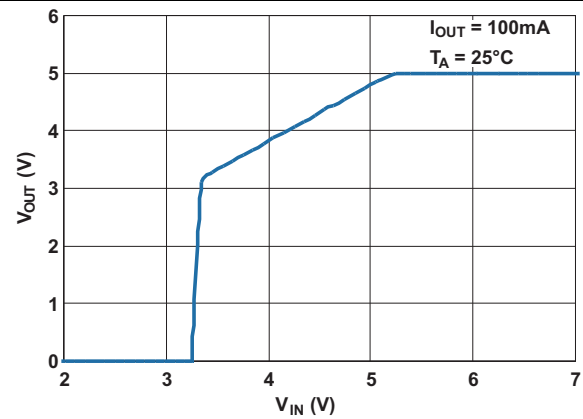
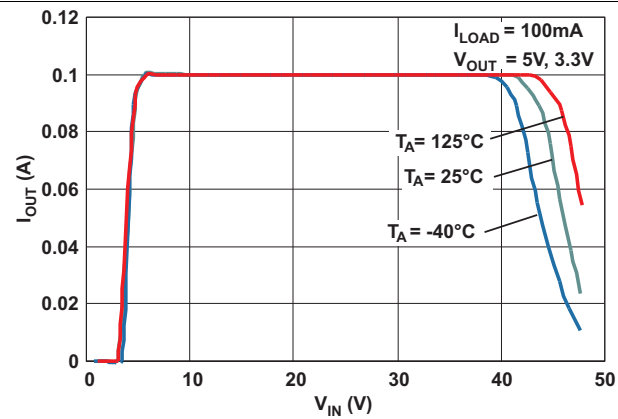
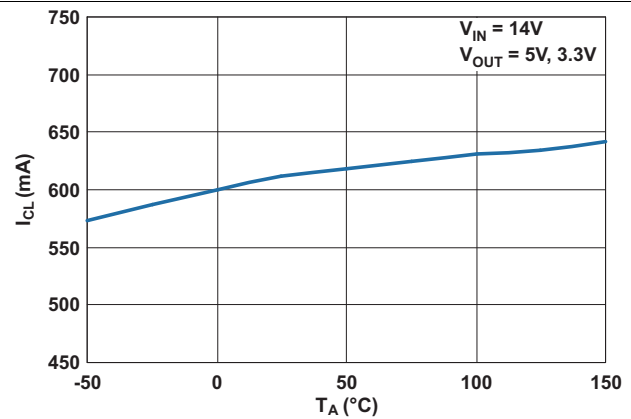
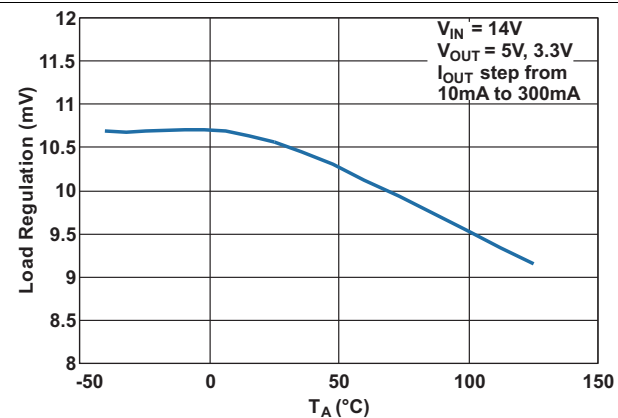
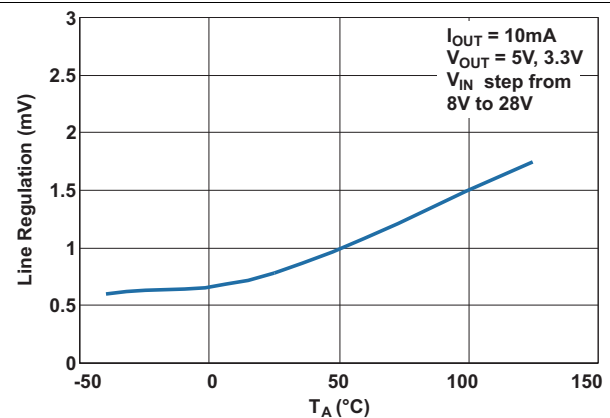


Figure 6. Dropout Voltage vs Load Current ⁽¹⁾

(1) Dropout voltage is measured when the output voltage drops by 100 mV from the regulated output voltage level. (For example, the dropout voltage for TPS7A6550 is measured when the output voltage drops down to 4.9 V from 5 V.)

Typical Characteristics (continued)

Figure 7. Output Voltage vs Ambient Air Temperature

Figure 8. Output Voltage vs Input Voltage

Figure 9. Output Current vs Input Voltage

Figure 10. Output Current Limit vs Ambient Air Temperature

Figure 11. Load Regulation vs Ambient Air Temperature

Figure 12. Line Regulation vs Ambient Air Temperature

Typical Characteristics (continued)

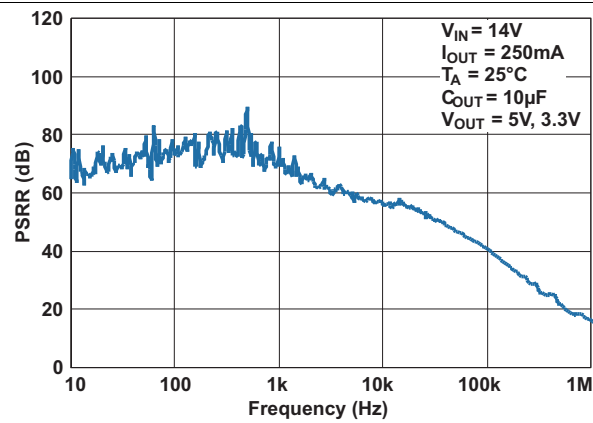


Figure 13. PSRR at Heavy Load Current

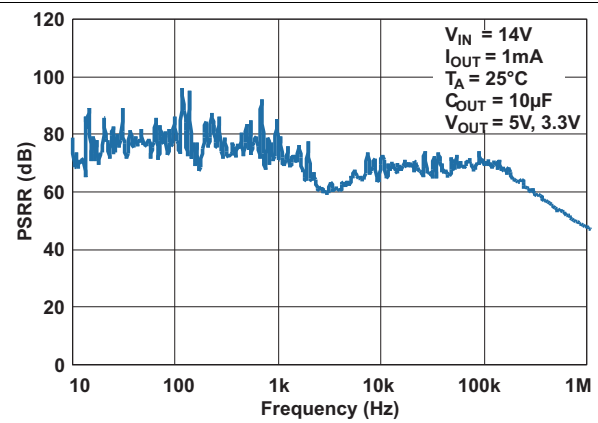


Figure 14. PSRR at Light Load Current

7 Detailed Description

7.1 Overview

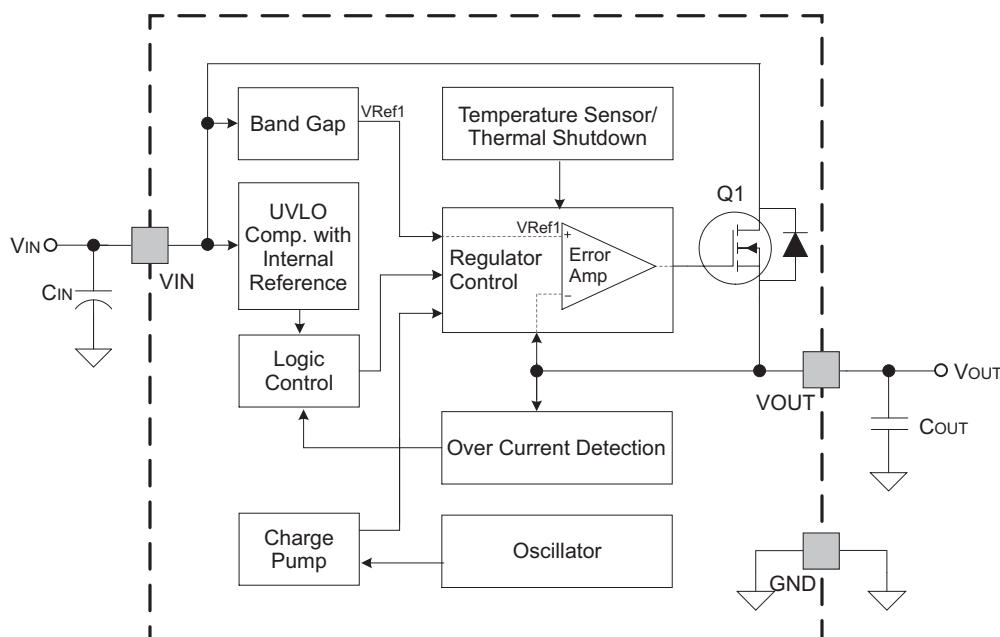
The TPS7A65-Q1 is a monolithic low-dropout linear voltage regulator designed for low-power consumption and quiescent current less than 25 μA in light-load applications. Because of an integrated fault protection, this device is well-suited in power supplies for various automotive applications.

This device is available in two fixed-output-voltage versions as follows:

- 5-V output version (TPS7A6550-Q1)
- 3.3-V output version (TPS7A6533-Q1)

See [Feature Description](#) for full descriptions of the features of the TPS7A65-Q1 voltage regulator.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Power Up

During power up, the regulator incorporates a protection scheme to limit the current through the pass element and output capacitor. When the input voltage exceeds a certain threshold ($V_{IN(PowerUp)}$) level, the output voltage begins to ramp up; see [Figure 15](#).

Feature Description (continued)

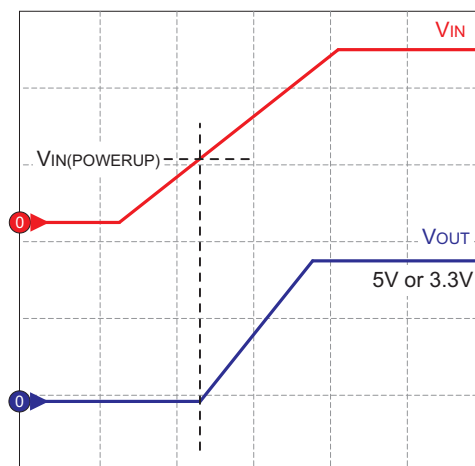


Figure 15. Power-Up Sequence

7.3.2 Charge-Pump Operation

This device has an internal charge pump that turns on or off depending on the input voltage and the output current. The charge pump switching circuitry does not cause conducted emissions to exceed required thresholds on the input voltage line. For a given output current, the charge pump stays on at lower input voltages and turns off at higher input voltages. The charge-pump switching thresholds are hysteretic. [Figure 16](#) and [Figure 17](#) show typical switching thresholds for the charge pump at light ($I_{OUT} < \text{approximately } 2 \text{ mA}$) and heavy ($I_{OUT} > \text{approximately } 2 \text{ mA}$) loads, respectively.

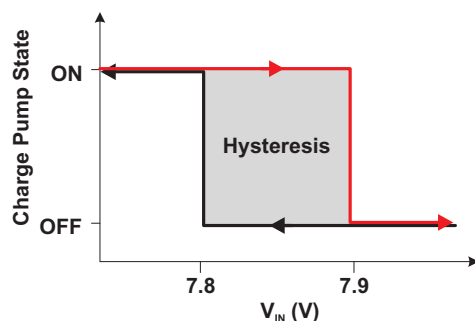


Figure 16. Charge-Pump Operation at Light Loads

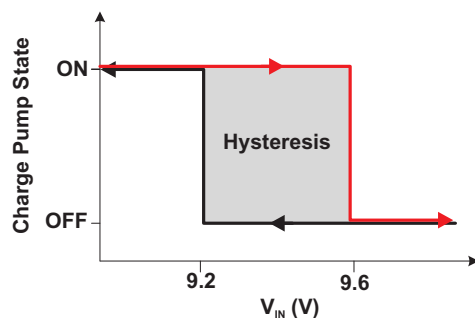


Figure 17. Charge-Pump Operation at Heavy Loads

Feature Description (continued)

7.3.3 Low-Power Mode

At light loads and high input voltages ($V_{IN} > \text{approximately } 8 \text{ V}$ such that charge pump is off) the device operates in the low-power mode and the quiescent current consumption decreases to $25 \mu\text{A}$ (typical) as shown in Table 1.

Table 1. Typical Quiescent Current Consumption

I_{OUT}	CHARGE PUMP ON	CHARGE PUMP OFF
$I_{OUT} < \text{approximately } 2 \text{ mA}$ (light load)	$250 \mu\text{A}$	$25 \mu\text{A}$ (low-power mode)
$I_{OUT} > \text{approximately } 2 \text{ mA}$ (heavy load)	$280 \mu\text{A}$	$70 \mu\text{A}$

7.3.4 Undervoltage Shutdown

This device has an integrated undervoltage lockout (UVLO) circuit to shut down the output if the input voltage (V_{IN}) falls below an internally fixed UVLO threshold level ($V_{IN-UVLO}$) as shown in Figure 18. This ensures that the regulator does not latch into an unknown state during low input-voltage conditions. The regulator normally powers up when the input voltage exceeds the $V_{IN(PowerUp)}$ threshold.

7.3.5 Low-Voltage Tracking

At low input voltages, the regulator drops out of regulation, and the output voltage tracks input minus a voltage based on the load current (I_{OUT}) and switch resistance (R_{SW}) as shown in Figure 18. This allows for a smaller input capacitor and can possibly eliminate the need of using a boost converter during cold-crank conditions.

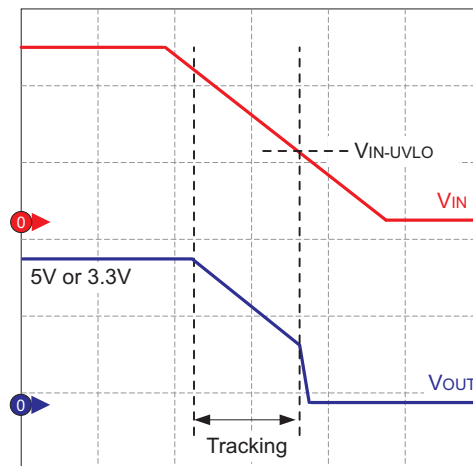


Figure 18. Undervoltage Shutdown and Low-Voltage Tracking

7.3.6 Integrated Fault Protection

This device features integrated fault protection to make them ideal for use in automotive applications. To keep the device in a safe area of operation during certain fault conditions, the device uses internal current limit protection and current limit foldback to limit the maximum output current. This protects the device from excessive power dissipation. For example, during a short-circuit condition on the output, limiting current through the pass element to I_{CL} protects the device from excessive power dissipation.

7.3.7 Thermal Shutdown

This device incorporates a thermal shutdown (TSD) circuit as a protection from overheating. For continuous normal operation, the junction temperature should not exceed the TSD trip point. If the junction temperature exceeds the TSD trip point, the output turns off. When the junction temperature falls below the TSD trip point, the output turns on again. Figure 19 shows this.

Feature Description (continued)

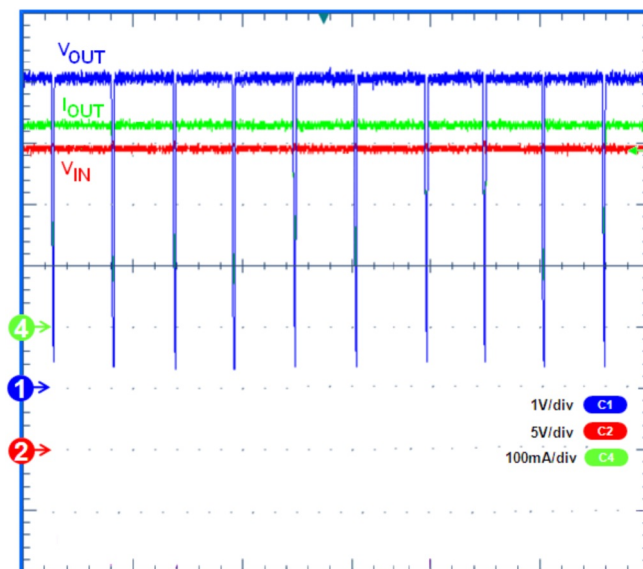


Figure 19. Thermal Cycling Waveform for TPS7A6550-Q1 ($V_{IN} = 24\text{ V}$, $I_{OUT} = 300\text{ mA}$, $V_{OUT} = 5\text{ V}$)

7.4 Device Functional Modes

7.4.1 Operation With V_{IN} Lower Than 4 V

The TPS7A65-Q1 device operates with input voltage above 4 V. The typical UVLO voltage is 3.16 V, the device can operate at input voltage lower than 4 V. But at input voltage below the actual UVLO, the device shuts down.

7.4.2 Operation With V_{IN} Larger Than 4 V

When V_{IN} is greater than 4 V, if the input voltage is higher than V_{OUT} plus the dropout voltage, the output voltage is equal to the set value. Otherwise, the output voltage is equal to V_{IN} minus the dropout voltage.

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The TPS7A65-Q1 is a low-dropout linear voltage regulator designed for low power consumption and quiescent current less than 25 μA in light-load applications. This device features integrated overcurrent protection and a design to achieve stable operation even with low-ESR ceramic output capacitors. A low-voltage tracking feature allows for a smaller input capacitor and can possibly eliminate the need of using a boost converter during cold crank conditions. Because of these features, this device is well-suited in power supplies for various automotive applications.

8.2 Typical Application

A typical application circuit for TPS7A65-Q1 is [Figure 20](#). Depending on the end application, one may use different values of external components. An application may require a larger output capacitor during fast load steps to prevent the output from temporarily dropping down. TI recommends a low-ESR ceramic capacitor with dielectric of type X5R or X7R. The user can additionally connect a bypass capacitor at the output to decouple high-frequency noise as per the end application.

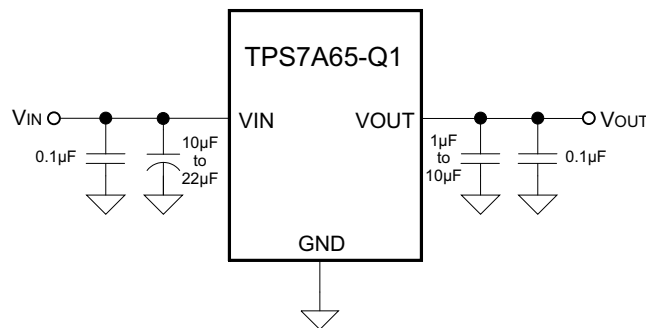


Figure 20. Typical Application Schematic

8.2.1 Design Requirements

[Table 2](#) lists the parameters for this design example.

Table 2. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input voltage range	7 V to 40 V
Output voltage	3.3 V, 5 V
Output current rating	300 mA maximum
Output capacitor range	1 μF to 10 μF

8.2.2 Detailed Design Procedure

When using the TPS7A6533-Q1, TPS7A6550-Q1, TI recommends adding a 10- μ F to 22- μ F capacitor to the input to keep the input voltage stable. TI also recommends adding a 1- μ F to 10- μ F low ESR ceramic capacitor to get a stable output.

8.2.3 Application Curve

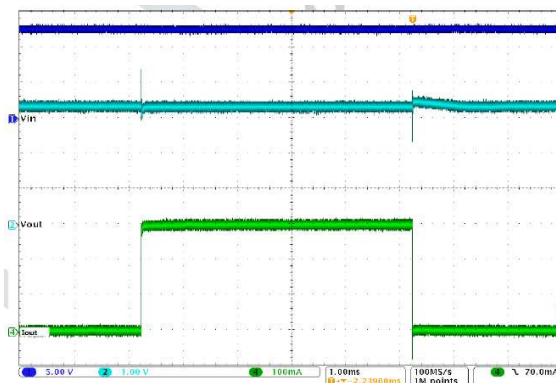


Figure 21. TPS7A6533-Q1 Load Transient Waveform

9 Power Supply Recommendations

The device is designed to operate from an input-voltage supply range from 7 V to 40 V. This input supply must be well regulated. If the input supply is located more than a few inches from the TPS7A65-Q1 device, TI recommends adding an electrolytic capacitor with a value of 10 μ F and a ceramic bypass capacitor at the input.

10 Layout

10.1 Layout Guidelines

For the LDO power supply, especially these high voltage and large current ones, layout is an important step. If layout is not carefully designed, the regulator could not deliver enough output current because of the thermal limitation. To improve the thermal performance of the device, and maximize the current output at high ambient temperature, TI recommends spreading the thermal pad as large as possible and putting enough thermal vias on the thermal pad.

10.1.1 Power Dissipation and Thermal Considerations

Calculate the power dissipated in the device using [Equation 1](#).

$$P_D = I_{OUT} \times (V_{IN} - V_{OUT}) + I_{QUIESCENT} \times V_{IN}$$

where

- P_D = continuous power dissipation
- I_{OUT} = output current
- V_{IN} = input voltage
- V_{OUT} = output voltage
- $I_{QUIESCENT}$ = quiescent current.

(1)

$I_{QUIESCENT} \ll I_{OUT}$; therefore, ignore the term $I_{QUIESCENT} \times V_{IN}$ in [Equation 1](#).

For a device under operation at a given ambient air temperature (T_A), calculate the junction temperature (T_J) using [Equation 2](#).

$$T_J = T_A + (\theta_{JA} \times P_D)$$

where

- θ_{JA} = junction-to-ambient air thermal impedance.

(2)

Calculate the rise in junction temperature due to power dissipation using [Equation 3](#).

$$\Delta T = T_J - T_A = (\theta_{JA} \times P_D)$$

(3)

For a given maximum junction temperature (T_{J-Max}), calculate the maximum ambient air temperature (T_{A-Max}) at which the device can operate using [Equation 4](#).

$$T_{A-Max} = T_{J-Max} - (\theta_{JA} \times P_D)$$

(4)

Example

If $I_{OUT} = 100$ mA, $V_{OUT} = 5$ V, $V_{IN} = 14$ V, $I_{QUIESCENT} = 250$ μ A and $\theta_{JA} = 30^\circ\text{C/W}$, the continuous power dissipated in the device is 0.9 W. The rise in junction temperature due to power dissipation is 27°C . For a maximum junction temperature of 150°C , maximum ambient air temperature at which the device can operate is 123°C .

For adequate heat dissipation, TI recommends soldering the power pad (exposed heat sink) to the thermal land pad on the PCB. Doing this provides a heat conduction path from the die to the PCB and reduces overall package thermal resistance. [Figure 22](#) shows power derating curves for the TPS7A65-Q1 family of devices in the KVVU (DPAK) package.

Layout Guidelines (continued)

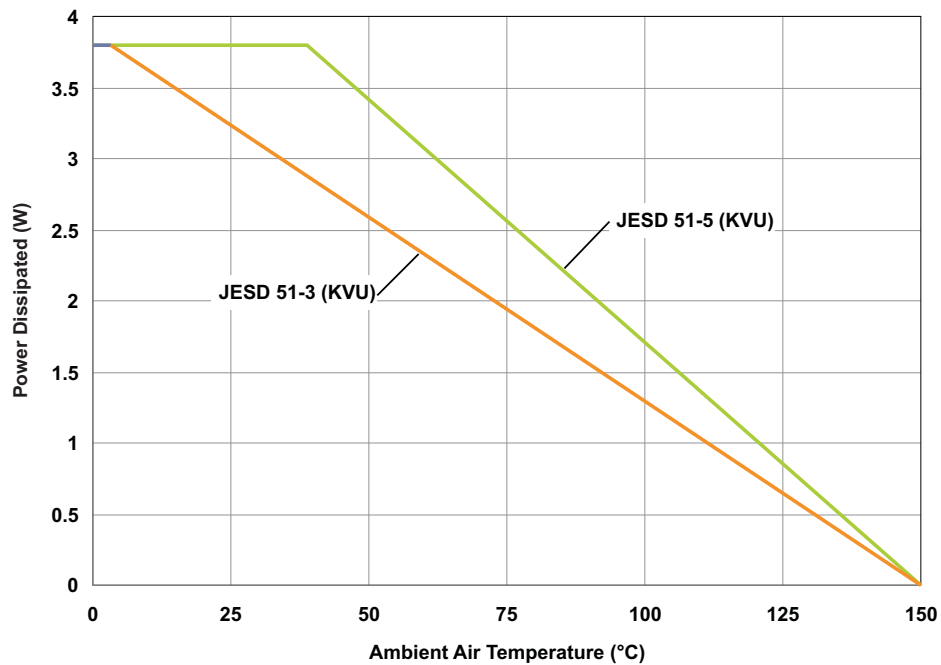


Figure 22. Power Derating Curves

For optimum thermal performance, TI recommends using a high-K PCB with thermal vias between the ground plane and solder pad or thermal land pad. [Figure 23](#) (a) and (b) show this. Further, a design can improve the heat-spreading capabilities of a PCB considerably by using a thicker ground plane and a thermal land pad with a larger surface area.

Layout Guidelines (continued)

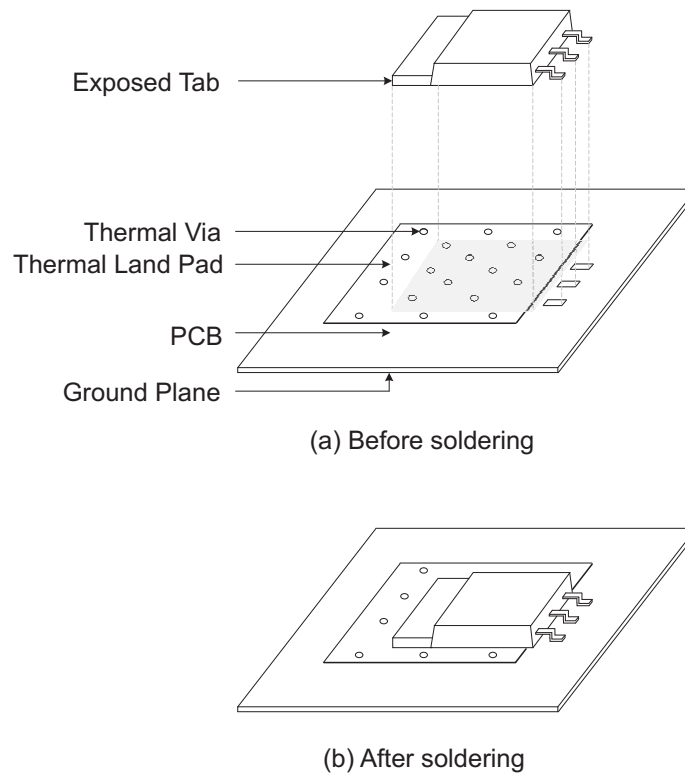


Figure 23. Using a Multilayer PCB and Thermal Vias for Adequate Heat Dissipation

Keeping other factors constant, the surface area of the thermal land pad contributes to heat dissipation only to a certain extent. Figure 24 shows the variation of θ_{JA} with surface area of the thermal land pad (soldered to the exposed pad) for the KVV package.

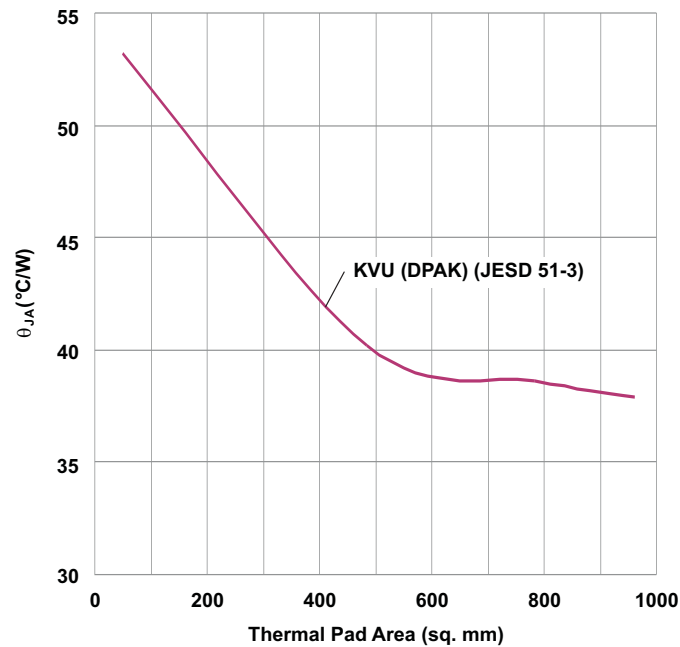


Figure 24. θ_{JA} vs Thermal Pad Area

10.2 Layout Example

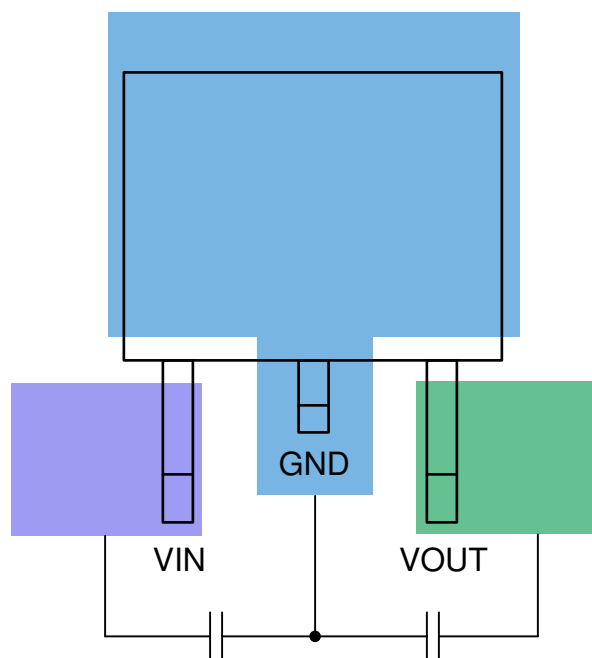


Figure 25. Layout Recommendation

11 器件和文档支持

11.1 接收文档更新通知

要接收文档更新通知，请导航至 ti.com.cn 上的器件产品文件夹。单击右上角的通知我进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

11.2 社区资源

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

11.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此数据表的浏览器版本，请查阅左侧的导航栏。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS7A6533QKVURQ1	Active	Production	TO-252 (KVU) 3	2500 LARGE T&R	Yes	SN	Level-3-260C-168 HR	-40 to 125	7A6533Q1
TPS7A6533QKVURQ1.A	Active	Production	TO-252 (KVU) 3	2500 LARGE T&R	Yes	SN	Level-3-260C-168 HR	-40 to 125	7A6533Q1
TPS7A6550QKVURQ1	Active	Production	TO-252 (KVU) 3	2500 LARGE T&R	Yes	SN	Level-3-260C-168 HR	-40 to 125	7A6550Q1
TPS7A6550QKVURQ1.A	Active	Production	TO-252 (KVU) 3	2500 LARGE T&R	Yes	SN	Level-3-260C-168 HR	-40 to 125	7A6550Q1

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

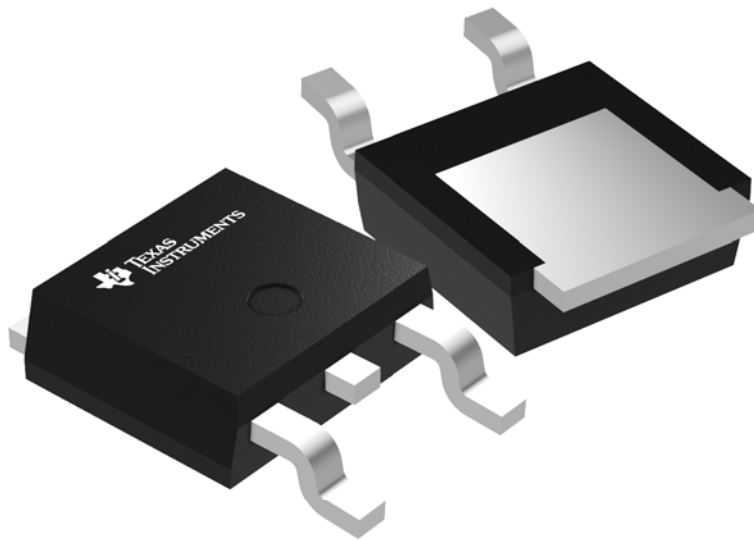
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS7A6533QKVURQ1	TO-252	KVU	3	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2
TPS7A6550QKVURQ1	TO-252	KVU	3	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS7A6533QKVURQ1	TO-252	KVU	3	2500	340.0	340.0	38.0
TPS7A6550QKVURQ1	TO-252	KVU	3	2500	340.0	340.0	38.0



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

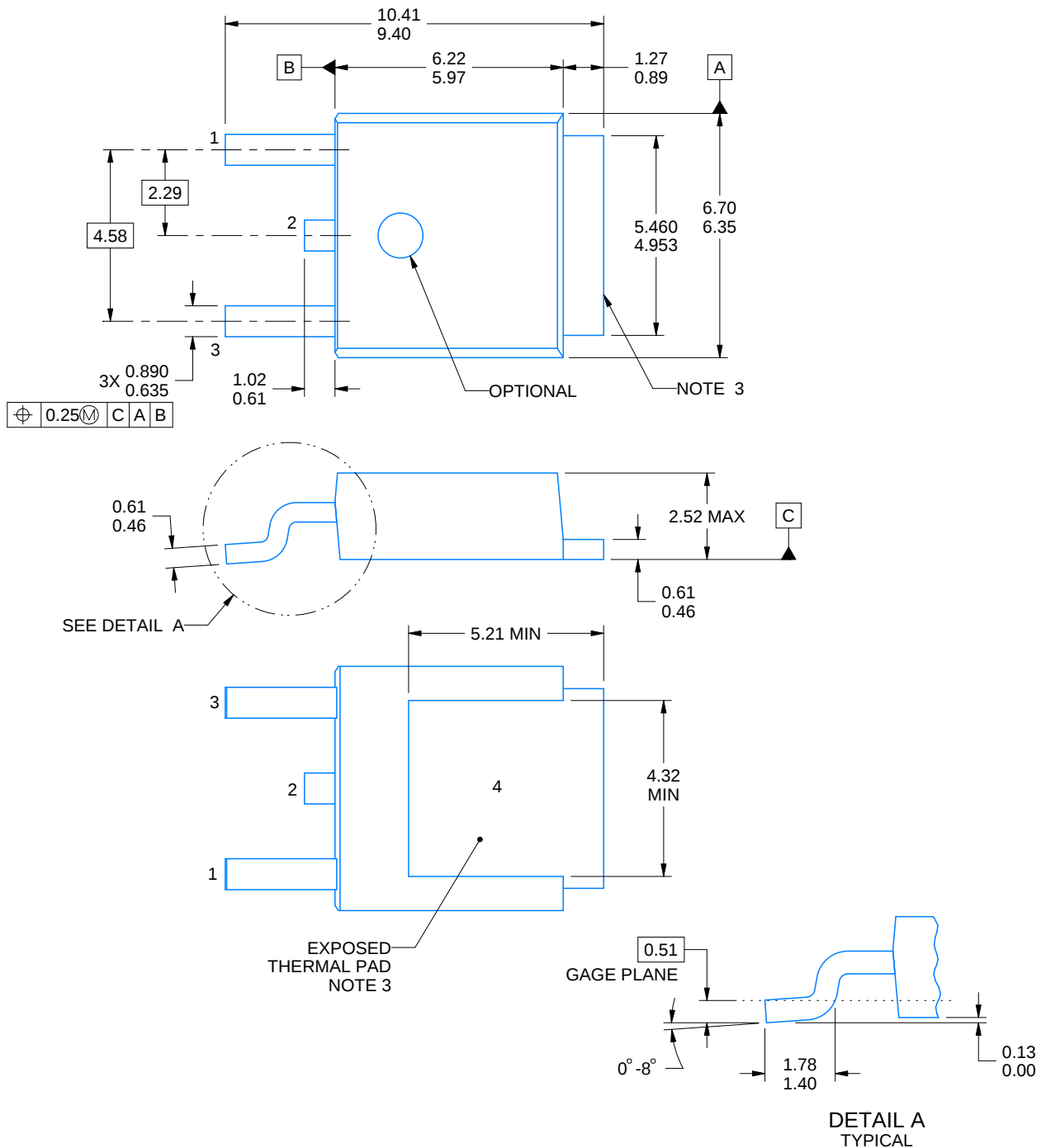


KVU0003A

PACKAGE OUTLINE

TO-252 - 2.52 mm max height

TO-252



4218915/A 02/2017

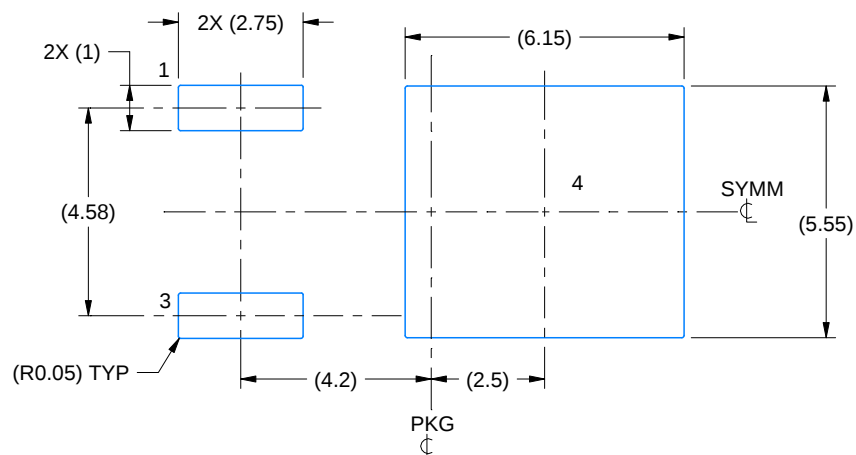
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Shape may vary per different assembly sites.
4. Reference JEDEC registration TO-252.

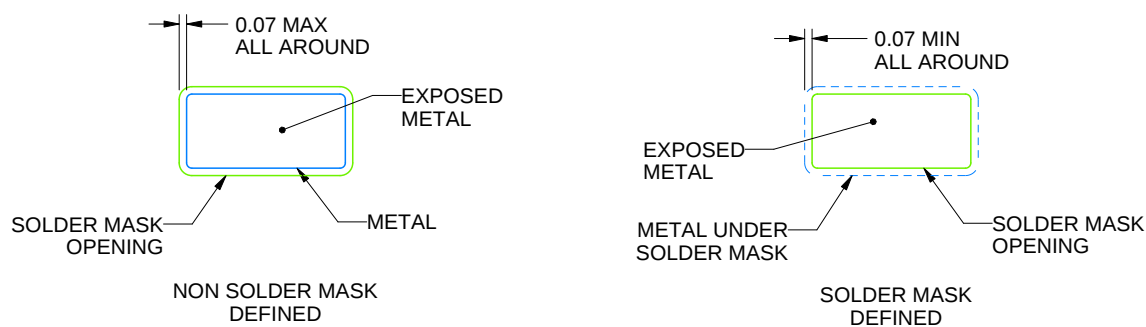
KVU0003A

TO-252 - 2.52 mm max height

TO-252



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:6X



SOLDER MASK DETAILS
NOT TO SCALE

4218915/A 02/2017

NOTES: (continued)

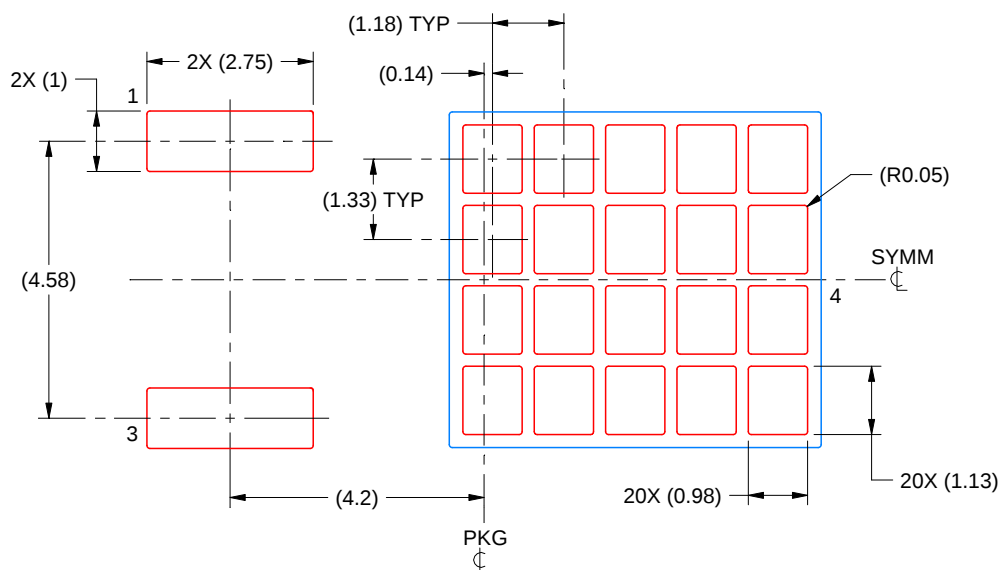
5. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002(www.ti.com/lit/slm002) and SLMA004 (www.ti.com/lit/slma004).
6. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

KVU0003A

TO-252 - 2.52 mm max height

TO-252



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
65% PRINTED SOLDER COVERAGE BY AREA
SCALE:8X

4218915/A 02/2017

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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